

TECHNICAL BID PROFORMA

Tender No. GTB10/CHRIS/2023/104/TSMC65NM

Item Name: TSMC 65nm gp RF Shared Block

1.0 Technical Compliance:

S.No	Foundry	TSMC	Complied/Not Complied	Reference Page No
1.	Technology (nm)	65		
2.	Flavor	MS RFGP		
3.	Metal	1p9m_6X1Z1U		
4.	Bump	No		
5.	Wire bond or Flip chip	Wire bond		
6.	Die x (mm)	-		
7.	Die y (mm)	-		
8.	Area (mm2)	17.00		
9.	Core (V)	1.0		
10.	I/O (V)	2.5		
11.	Wafer quantity	1		
12.	Sample quantity	100		
13.	Back grid thickness (mils)	12		

Die Details

1.	MOM caps used in the design. TSMC MOM caps are used which has M1-M7 metal layers.		
2.	Inductors are used in the design but not in AP layer.		
3.	45-degree metal routing lines are not used.		
4.	AP layer exist in the data base including the pads and its thickness is 14.5KA		
5.	Seal ring is included in the GDSII.		

**SIGNATURE OF BIDDER ALONG WITH
SEAL OF THE COMPANY WITH DATE**